



IPC-2292A

Design Standard for Printed Electronics on Flexible Substrates

Developed by the Flexible Printed Electronics Design Standard Task Group (D-61a) of the Printed Electronics Committee (D-60) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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Table of Contents

1	SCOPE	1	3.5.4	Test Points and Connectors	11
1.1	Purpose	1	3.6	Layout Evaluation	11
1.2	Classification	1	3.6.1	Layout Design	11
1.3	Measurement Units	1	3.6.2	Feasibility Density Evaluation	12
1.4	Definition of Requirements	1	4	MATERIALS	12
1.5	Process Control Requirements	1	4.1	Material Selection	12
1.6	Order of Precedence	1	4.1.1	Substrate Material Options	12
1.6.1	Conflict	2	4.1.2	Functional Material Options	14
1.6.2	Clause References	2	4.2	Flex Applications	14
1.6.3	Procurement Documentation	2	4.2.1	Stretch and Elongation	14
1.6.4	Appendices	2	4.2.2	Crease and Crumple	14
1.7	Quality Conformance	2	4.2.3	Gap Bridging Applications	14
1.8	Abbreviations and Acronym	2	4.2.4	Via Hole Aspect Ratio/Material Deposit Aspect Ratio	14
1.9	Terms and Definitions	2	4.2.5	Process Compatibility	15
1.9.1	Conductive Adhesive	2	4.2.6	Vertical Transition Angles	15
1.9.2	Crease	2	4.3	Materials Deposition Methods	15
1.9.3	Panelization	2	4.4	Contact Resistance	15
1.9.4	Substrate	2	4.5	Ink-to-Ink Compatibility	16
1.10	Printed Electronics Types	2	4.6	Ink-to-Substrate Compatibility	16
1.11	Standard Printed Electronics Design (SPED) Classifications	2	4.7	Ink Properties	16
1.11.1	Standard Printed Electronic Design (SPED) 1 ...	3	4.8	Dielectric Materials	16
1.11.2	Standard Printed Electronic Design (SPED) 2 ...	3	4.8.1	Dielectric Filaments	16
1.11.3	Standard Printed Electronic Design (SPED) 3 ...	4	4.8.2	Dielectric Ink Materials	16
1.11.4	Standard Printed Electronics Design (SPED) ...	4	4.9	Adhesives	16
2	APPLICABLE DOCUMENTS	5	4.9.1	Liquid Adhesives	16
2.1	IPC	5	4.9.2	Flexible Adhesive Bonding Films (Dry-Film Adhesive)	17
2.2	Joint Standards	5	4.9.3	Pressure-Sensitive Adhesives (PSAs)	17
2.3	ASTM International	5	4.10	Conductive Materials	17
2.4	SAE International	6	4.10.1	Conductive Inks Functioning by Percolation ...	17
2.5	NCSL International	6	4.10.2	Conductive Inks Functioning by Sintering	17
3	GENERAL REQUIREMENTS	6	4.10.3	Conductive Filaments (Wires, Coated Wires or Conductive Filaments)	18
3.1	Design Considerations	6	4.10.4	Conductive Films, Foils and Grids	18
3.2	Schematic/Logic Diagram	7	4.10.5	Printed Conductive Seed Layers for Plating (Print and Plate)	18
3.3	Parts List	7	4.10.6	Conductive Interfaces and Out-of-Plane Interconnects	18
3.4	Test Requirement Considerations	7	4.10.7	Isotropic Conductive Adhesives	19
3.5	Test Requirement Considerations	7	4.10.8	Anisotropic Conductive Adhesives	19
3.5.1	Electrical	7	4.11	Operations Following Plating	19
3.5.2	Printed Electronic Assembly Testability	10			
3.5.3	Functional Testing (FCT)	11			

4.12	Coatings	19	8.2.1	Automatic Assembly	28
4.12.1	Carbon for Printed Ag	19	8.2.2	Orientation	30
4.12.2	Conductive Coatings for Shielding	19	8.2.3	Accessibility	30
4.12.3	Organic Protective Coatings	19	8.2.4	Design Envelope	30
4.12.4	Conformal Coating, Spray Coats	19	8.2.5	Flush Mounting Over Conductive Areas	30
4.13	Other Cover Materials	19	8.2.6	Clearances	30
4.13.1	Coverlay	19	8.2.7	Physical Support	30
4.13.2	Coverfilm	19	8.2.8	Other Concerns	30
4.13.3	Covercoat	19	8.3	General Attachment Requirements	30
4.14	Other Printed Materials	19	8.3.1	Thermal Processing Considerations	30
4.15	Marking and Legend	20	8.3.2	Fastening Hardware	30
5	MECHANICAL AND PHYSICAL PROPERTIES	20	8.3.3	Stiffeners	31
5.1	Fabrication Requirements	20	8.3.4	Interconnects	31
5.1.1	Printed Flex Fabrication – Sheet Form	20	8.3.5	Component Selection Considerations	32
5.1.2	Printed Flex Roll-to-Roll Fabrication	20	9	HOLES/INTERCONNECTIONS	32
5.2	Product/Printed Flex Configuration	20	9.1	Printed Land Requirements	32
5.2.1	Circuit Profile (Outline)	20	9.2	Holes	32
5.2.2	Flexible Areas	21	9.2.1	Unsupported Holes	32
5.2.3	Forming Bends	23	9.2.2	Printed Through-Holes	33
6	ELECTRICAL PROPERTIES	24	10	DOCUMENTATION	33
6.1	Electrical Considerations	24	10.1	Special Tooling	33
6.1.1	Electrical Performance	24	10.2	Layout	33
6.1.2	Power Distribution Considerations	24	10.2.1	Viewing	33
6.1.3	Circuit Type Considerations	24	10.2.2	Accuracy and Scale	33
6.2	Conductive Material Requirements	25	10.2.3	Model and Drawing Notes	33
6.3	Electrical Clearance	25	10.2.4	Automated-Layout Techniques	34
6.4	Impedance Controls	25	10.3	Deviation Requirements	34
6.5	Printed Components	26	10.4	Phototool Considerations	34
6.5.1	Printed Resistors	26	10.4.1	Artwork Master Files	34
6.5.2	Printed Capacitors	26	10.4.2	Coating Phototools	34
6.5.3	Printed Inductors	26	11	QUALITY ASSURANCE	34
6.5.4	Printed Active Components	26	11.1	Material Quality Assurance	34
7	THERMAL MANAGEMENT	26	11.2	Statistical Process Control (SPC)	34
7.1	Cooling Mechanisms	27	11.3	Build and Manufacturing Controls	35
7.1.1	Conduction	27	11.4	Conformance Test Coupons	35
7.1.2	Radiation	27	11.4.1	Individual Coupon Design	35
7.1.3	Convection	27	11.4.2	Coupon Quantity and Location	35
7.1.4	Altitude Effects	27	11.4.3	Process Control Test Coupon	35
7.2	Heat Dissipation Considerations	27	11.4.4	Tolerances and Reporting Data	36
8	COMPONENT AND ASSEMBLY ISSUES	28	11.4.5	Coupon Identification	36
8.1	Lands for Surface-Mount Components	28	11.5	Responsibility for Inspection	36
8.2	General Placement Requirements	28	11.6	Test Equipment and Inspection Facilities	36

11.7 Preparation of Samples 36

11.8 Standard Laboratory Conditions 36

11.9 Tolerances 36

11.10 Qualification Inspection 36

11.11 Failures 36

11.12 User Sampling Plan 36

11.13 Noncompliance 36

11.14 Reduction of Quality Conformance Testing 36

11.15 Inspection Methodology 37

11.15.1 Process Verification Inspection 37

11.15.2 Visual Inspection 37

11.15.3 Magnification Aids 37

11.15.4 Acceptance and Test Activities 37

11.16 Storage Conditions 37

Appendix A Testability Requirements Considerations and Design Complexity 38

Appendix B Sample Layout Views for Printed Electronic Designs 40

Appendix C Index of Acronyms and Abbreviations 44

Figures

Figure 1-1 Standard Printed Electronic Design (SPED) 1 3

Figure 1-2 Standard Printed Electronic Design (SPED) 2 4

Figure 1-3 Standard Printed Electronics Design (SPED) 3 4

Figure 1-4 Example of Printed Electronic Using Every Standard Printed Electronic Design (SPED) Type in One Device 4

Figure 3-1 Rounded Probe and Pin Probe 10

Figure 4-1 Cross-Sectional View of a Representative Construction Identifying Material Types . . . 12

Figure 4-2 Meander Pattern 14

Figure 4-3 Hole Aspect Ratio 15

Figure 4-4 Material Deposit Aspect Ratio 15

Figure 4-5 Printed Conductive Network and Microstructure for Polymer Thick Film (PTF) Inks (Top) and Metalorganic Inks (Bottom) 18

Figure 5-1 Circuits Nested on a Panel Sheet 20

Figure 5-2 Relief Radii 20

Figure 5-3 Material Added for Increased Tear Resistance 21

Figure 5-4 Conductors in Bend Areas 22

Figure 5-5 Neutral Axis Ideal Construction 22

Figure 5-6 Printed Connector I-Beaming (Left) vs Staggered (Right) 23

Figure 5-7 Irregular Folds 23

Figure 6-1 Voltage/Ground Distribution Concepts 24

Figure 8-1 Component Interconnections 31

Figure 8-2 Two Examples of Ramps 32

Figure 11-1 Systematic Path for Implementation of Statistical Process Control (SPC) 35

Figure A.1 In-Circuit Test (ICT) Pads 38

Figure A.2 Connectors/Tails 39

Figure A.4 Example of Test Starting Points 39

Figure A.3 Test Header Pins 39

Figure B.1 Overall Dimensions 40

Figure B.2 Key Circuit 41

Figure B.3 Light-Emitting Diode (LED) Circuit 42

Figure B.4 Key Schematic (Top) and Light-Emitting Diode (LED) Schematic (Bottom) 43

Figure B.5 Structure Drawing 43

Tables

Table 3-1 Comparisons of Test and Inspection Methods 11

Design Standard for Printed Electronics on Flexible Substrates

1 SCOPE

This standard establishes specific requirements for the design of printed electronic applications and their forms of component mounting and interconnecting structures on flexible substrates. Flexible substrates, as pertain to this standard, are materials, devices or functionalized circuitry which have some amount of flexibility or bendability (not rigid) but are not considered to be stretchable.

1.1 Purpose The requirements contained herein are intended to establish design principles and recommendations that **shall** be used in conjunction with the detailed requirements of a specific printed electronic application to produce detailed designs for the printed electronic. This standard is not intended for use as a performance specification nor as an acceptance document.

1.2 Classification IPC standards recognize that electrical and electronic assemblies are subject to classifications by intended end-item use. Three general end-product classes have been established to reflect differences in manufacturability, complexity, functional performance requirements, and verification (inspection/test) frequency. It should be recognized that there may be overlaps of equipment between classes.

CLASS 1 General Electronic Products

Includes products suitable for applications where the major requirement is function of the completed assembly.

CLASS 2 Dedicated Service Electronic Products

Includes products where continued performance and extended life is required, and for which uninterrupted service is desired but not critical. Typically, the end-use environment would not cause failures.

CLASS 3 High Performance/Harsh Environment Electronic Products

Includes products where continued high performance or performance-on-demand is critical, equipment downtime cannot be tolerated, end-use environment may be uncommonly harsh, and the equipment must function when required, such as life support or other critical systems.

1.3 Measurement Units All dimensions and tolerances in this specification are expressed in hard SI (metric) units and bracketed soft imperial [inch] units. Users of this specification are expected to use metric dimensions. All dimensions ≥ 1 mm [0.0394 in] will be expressed in millimeters and inches. All dimensions < 1 mm [0.0394 in] will be expressed in micrometers and microinches.

1.4 Definition of Requirements The words **shall** or **shall not** are used in the text of this document wherever there is a requirement for materials, preparation, process control or acceptance.

The word “should” reflects recommendations and is used to reflect general industry practices and procedures for guidance only.

Line drawings and illustrations are depicted herein to assist in the interpretation of the written requirements of this Standard. The text takes precedence over the figures.

1.5 Process Control Requirements The primary goal of process control is to continually reduce variation in the processes, products, or services to provide products or processes meeting or exceeding user requirements. Process control tools such as IPC-9191 or other user-approved system may be used as guidelines for implementing process control.

A documented process control system, if established, **shall** define process control and corrective action limits.

This may or may not be a statistical process control system. The use of statistical process control (SPC) is optional and should be based on factors such as design stability, lot size, production quantities and the needs of the manufacturer (see 11.2).

When a decision or requirement is to use a documented process control system, failure to implement process corrective action and/or the use of continually ineffective corrective actions **shall** be grounds for disapproval of the process and associated documentation.

1.6 Order of Precedence The contract **shall** take precedence over this standard, referenced standards and drawings.

In the event of conflict, the following order of precedence applies:

- 1) Procurement as agreed and documented between user and supplier.
- 2) Master drawing, design brief or tech pack reflecting the user’s detailed requirements.
- 3) When invoked by the customer or per contractual agreement, this standard.

When documents other than this standard are cited, the order of precedence **shall** be defined in the procurement documents. The user can specify alternate acceptance criteria.

1.6.1 Conflict In the event of conflict between the requirements of this standard and the applicable drawing(s) and documentation, the applicable user-approved drawing(s) and documentation govern.

Some examples of documentation include the contract, purchase order, technical data package, engineering specification or performance specification. In the event of a conflict between the text of this standard and the applicable documents cited herein, the text of this standard takes precedence. In the event of conflict between the requirements of this standard and drawing(s) and documentation that has not been user approved, this standard governs.

1.6.2 Clause References When a clause in this document is referenced, its subordinate clauses apply, unless the requirement references specific subordinate clauses.

1.6.3 Procurement Documentation The procurement documentation **shall** provide sufficient information to the supplier so the supplier can produce printed boards containing embedded active and passive circuitry and ensure the user receives the desired product. The procurement documentation should specify the requirements that can be selected from within this standard.

1.6.3.1 Selection for Procurement For procurement purposes, performance class **shall** be specified in the procurement documentation. The documentation **shall** provide sufficient information to the supplier so that one can fabricate the printed board and ensure that the user receives the desired product. Information that should be included in the procurement documentation is shown in IPC-D-325.

1.6.4 Appendices Appendices to this standard are not binding requirements unless separately and specifically required by this standard, the applicable contracts, assembly drawing(s), documentation or purchase orders.

1.7 Quality Conformance This standard establishes a quality conformance system for suppliers to demonstrate the continual conformance of materials to the quality requirements of the standard. See Section 11 for quality conformance inspection requirements.

1.8 Abbreviations and Acronyms When used, periodic table elements are abbreviated in the standard. See Appendix C for full spellings of abbreviations (including elements) and acronyms used in this standard.

1.9 Terms and Definitions Terms and definitions **shall** be in accordance with IPC-T-51, IPC-T-50 and the following.

1.9.1 Conductive Adhesive The conductive material interconnects between component terminals and printed pad.

1.9.2 Crease To make a line, ridge or groove on a printed electronic device by adding pressure to fold the substrate or device.

1.9.3 Panelization A method used to reduce manufacturing costs. Panelization consists of a number or array of printed electronics devices which are grouped on a substrate panel. Panel optimizers may be used to determine the most efficient placement of the devices' arrays within the panel. The optimizer calculates all panel placement combinations based on the panel dimensions and the devices to be printed.

1.9.4 Substrate For purposes of this standard, a substrate is any conductive or nonconductive flexible manufactured part or base material. A variety of materials can be used as a base substrate, from traditional flexible printed board materials to paper and other flexible materials.

1.10 Printed Electronics Types Any printed electronics design will be incumbent on requirements from the customer, materials to be used and the printing processes. The following printed electronics types represent the known variations of printed electronics. These types cover all known processes for printing electronics (e.g., screen, aerosol, 3D, etc.). As other types or printing processes are made known, they will be added to this standardized list of types.

The printed electronics type **shall** be specified on the procurement document. If the printed electronics type is not designated below, a unique type designation will be used.

- *Printed electronics – Type 1:* Using printed electronics processes on a planar substrate
- *Printed electronics – Type 2:* Using printed electronics processes on a nonplanar substrate
- *Printed electronics – Type 3:* Using printed electronics processes to fully build and functionalize a device in a 3D space (no starting substrate)

1.11 Standard Printed Electronics Design (SPED) Classifications Standard print electronics design (SPED) types **shall** be in accordance with 1.11.1 through 1.11.3. For purposes of explanation, a basic variation of each SPED is shown in 1.11.1 through 1.11.3.